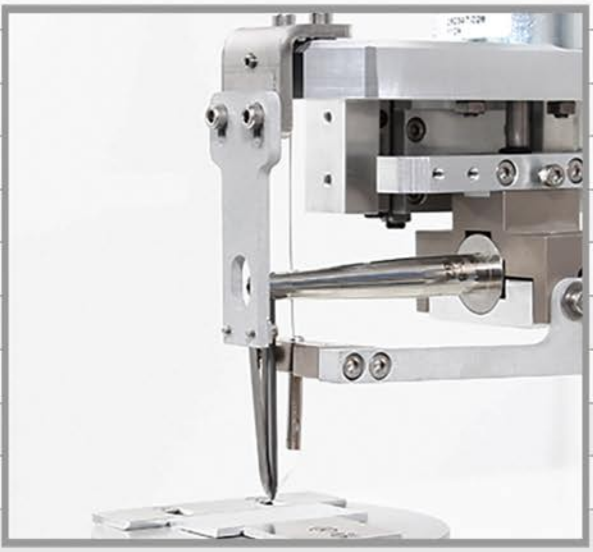
HB30 Heavy Wire Bonder

Motorized Z- & Y- Axes



- + 100µ to 500µ Aluminium Wire
- + 6,5" TFT Touch Screen
- + 100 Program Storage Capacities
- + Built in Dual Fiber Optic illuminator
- + Motorised Z Bond Head
- + Motorized Y travel for Step-Back loop control
- + 3:1 ratio X-Y manipulator
- + Loop Profile Programmable
- + Stitch bonding
- + Ribbon bonding
- + Semi-auto, Step and Manual Bonding Mode

HB30 Heavy Wire Bonder

The HB30 is a **Bench Top Size Wire Bonder**, ideal for laboratories, pilot and pre-production runs and small scale production lines. Easy operation with **TFT Touch Screen** Operator System. Direct access and simple adjustment to all bond parameters and programs.

Technical Specifications

Ultrasonic system	PLL US System
Utrasonic power	50 Watt Output
Bond time	0 - 10 sec.
Bond force	50 - 1800 cN
Aluminium wire diameter	100 to 500 µm
Ribbon size max.	300 x 1500 µm (Option 300 x 2000 µm)
Wire termination	Front Cut
Wire feed angle	90°
Motorized Y travel	Stepback up to 17 mm
Motorized Z travel	20 mm
Fine Table motion	15 mm
Mouse ratio	3:1 (Option 6:1)
Electrical Requirements	100 - 240V +/-10% 50/60 Hz 10A max.
Physical Dimensions	680 mm (27")W x 640 mm (25") D x 490 mm (19") H
Weight	Net 50 kg
Industry Standards	CE Standards

Accessories:

H50 Spotlight Targeting System

H51 Manual Z-Axis Control

H28 Stage Ø 90mm

H89 Video Targeting System

H52 Dynamic Search

Specifications are subject to change without prior notice

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Made in Germany